

OCT 25 2005

Patent

Docket No. MTI-31607

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Application of : Lee, Teck et al.  
Serial No. : 10/050,507  
Filing Date : January 16, 2002  
For : Elimination of RDL Using Tape Base Flip Chip on Flex for Die Stacking  
Examiner : THOMPSON, Craig  
Confirmation No. : 7687  
Group Art Unit : 2813

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**CERTIFICATION UNDER 37 CFR 1.8(a) and 1.10**

I hereby certify that, on the date shown below, this correspondence is being transmitted to Fax No. 571-273-8300 addressed to Examiner THOMPSON at the US Patent and Trademark Office.

Date: \_\_\_\_\_

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**STATUS INQUIRY**

Dear Sir:

This application was filed on January 16, 2002, and the last correspondence filed in this application is a Request for Continued Examination (RCE) submitted May 10, 2005.

More than **fifty-seven (57)** months (from the filing date), and **five (5)** months (from the mailing date of the RCE) have passed without receiving any communication from the U.S. Patent and Trademark Office. Please provide us with a status of this application.

Respectfully submitted,

Dated: October 25, 2005

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